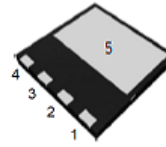




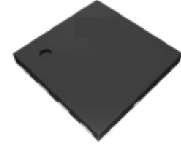
## Features

- Shorter recovery time
- High speed switching
- Low forward voltage
- High surge current capability
- Low forward voltage

## Outline ( DFN 8x8)



(Bottom View)



(Top View)

## Applications

- Power Factor Correction in SMPS
- Solar inverter
- Uninterruptible Power Supply
- Motor Drives
- Data Center

## Circuit Diagram



5: Cathode  
3,4: Anode  
1,2: NC

## Mechanical Characteristics

- DFN 8\*8 package
- Halogen Free
- Pb free lead plating ; RoHS compliant
- Packaging: Embossed Tape

## Marking Diagram

Laser Mark



LL : Assembly Lot code  
WW : Week  
YY : Year



## Parameter and Specification

### Absolute Maximum Rating<sup>(1)</sup>

Parameter	Symbol	Condition	Value	Unit
Repetitive peak reverse voltage	$V_{RM}$	$T_c=25^{\circ}C$	650	V
Continue forward current	$I_F$	$T_c=135^{\circ}C$	10	A
Surge non-repetitive forward current , sine half-wave	$I_{FSM}$	$T_c=25^{\circ}C, t_p=10ms, \text{Sine half wave}$	90	A
		$T_c=110^{\circ}C, t_p=10ms, \text{Sine half wave}$	72	
Surge repetitive forward current	$I_{FRM}$	$T_c=25^{\circ}C, t_p=10ms, \text{Sine half wave}$	40	A
$I^2t$ value	$\int I^2t$	$T_c=25^{\circ}C, t_p=10ms, \text{Sine half wave}$	40	$A^2s$
Total power dissipation	$P_D$	$T_c=25^{\circ}C$	96	W
		$T_c=110^{\circ}C$	42	
Junction temperature	$T_j$		175	$^{\circ}C$
Storage temperature	$T_{STG}$		-55 ~ 175	$^{\circ}C$

Note :

(1) Exceeding these ratings may damage the device.

### Thermal Characteristics

Parameter	Symbol	Condition	Typ.	Unit
Thermal resistance	$\theta_{jc}$	Junction - Case	1.5	$^{\circ}C / W$

**Electrical Characteristics**

Characteristic	Symbol	Condition	MIN	TYP	MAX	Unit
DC reverse voltage	$V_{DC}$	$T_j = 25^{\circ}C, I_R = 50\mu A$	650	-	-	V
Forward voltage	$V_F$	$T_j = 25^{\circ}C, I_F = 10A$	-	1.35	1.5	V
		$T_j = 150^{\circ}C, I_F = 10A$	-	1.6	-	
		$T_j = 175^{\circ}C, I_F = 10A$	-	1.7	-	
Reverse current	$I_R$	$T_j = 25^{\circ}C, V_R = 650V$	-	2	50	uA
		$T_j = 150^{\circ}C, V_R = 650V$	-	8	-	
		$T_j = 175^{\circ}C, V_R = 650V$	-	15	-	
Total capacity charge	$Q_C$	$T_j = 25^{\circ}C, V_R = 400V,$ $di/dt = 350A/\mu s$	-	24	-	nC
Total capacitance	$C_{TOT}$	$T_j = 25^{\circ}C, V_R = 1V,$ $F = 1MHz$	-	410	-	pF
		$T_j = 25^{\circ}C, V_R = 400V,$ $F = 1MHz$	-	40	-	
		$T_j = 25^{\circ}C, V_R = 650V,$ $F = 1MHz$	-	39	-	
Capacitance Stored Energy	$E_C$	$V_R = 400V$	-	4	-	$\mu J$



650V / 10A

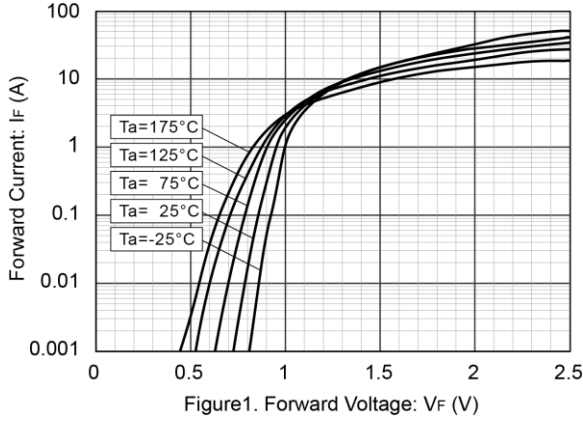
AGC010H06DC

SiC Schottky Barrier Diode

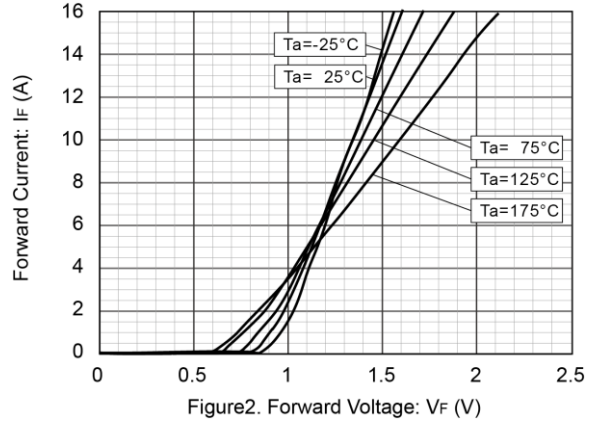
ACTRON TECHNOLOGY CORP.

### Electrical Characteristic Curves

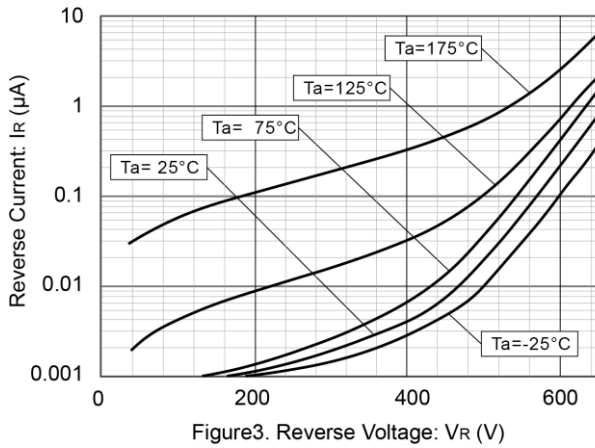
#### $V_F - I_F$ Characteristics



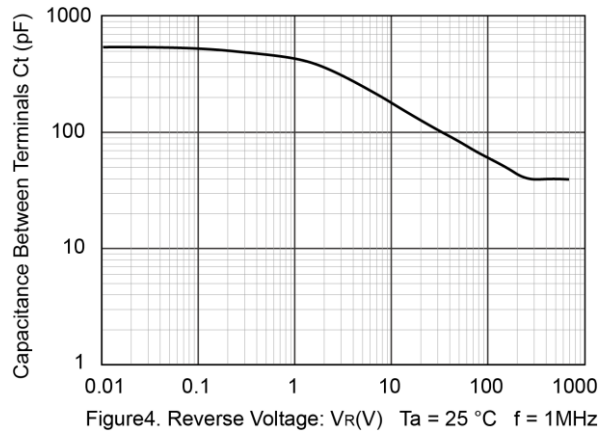
#### $V_F - I_F$ Characteristics



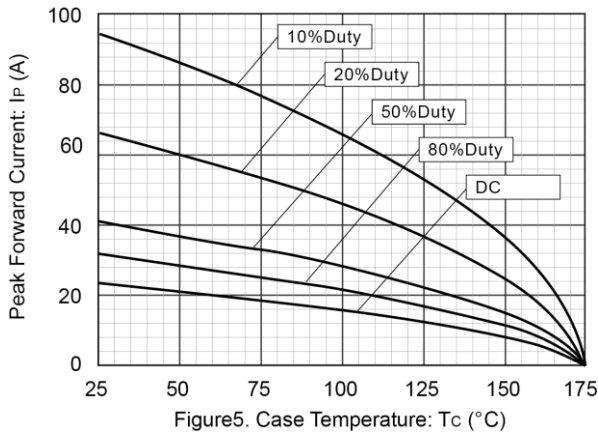
#### $V_R - I_R$ Characteristics



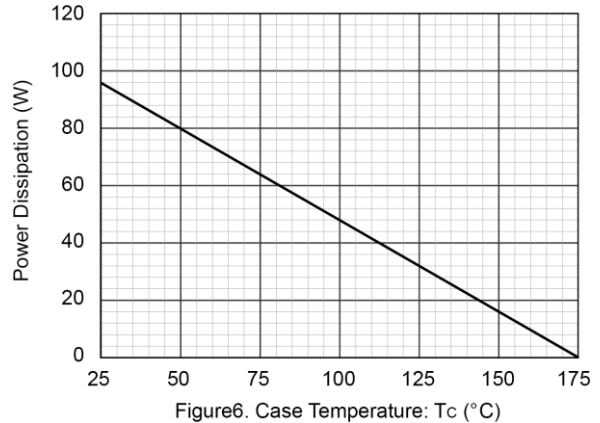
#### $V_R - C_t$ Characteristics



#### Maximum $I_P - T_C$ Characteristics



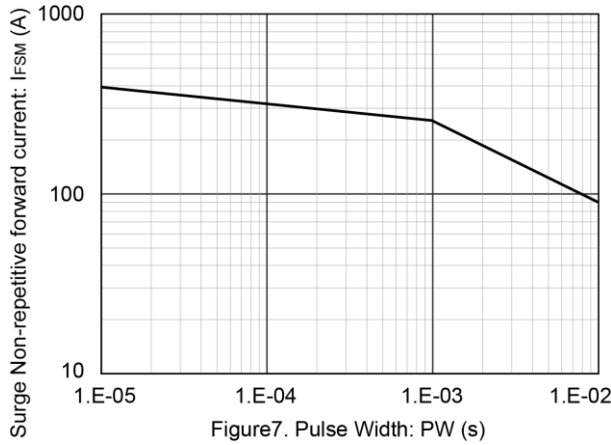
#### Power Dissipation



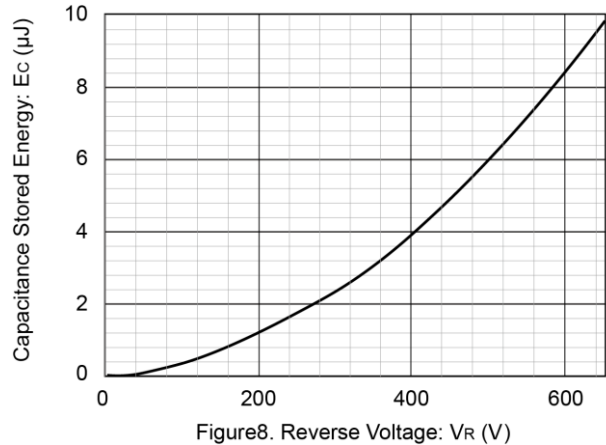


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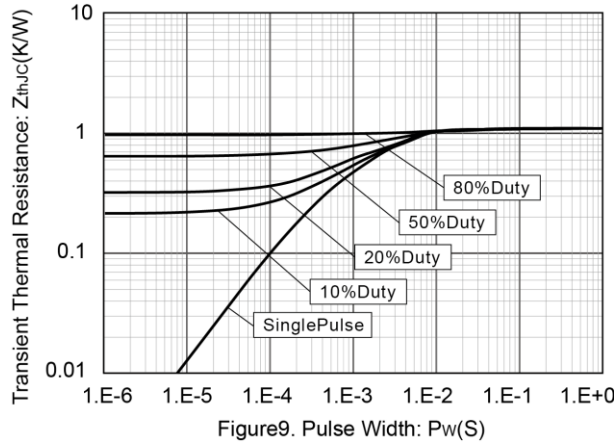
**I<sub>FSM</sub> – PW Characteristics**



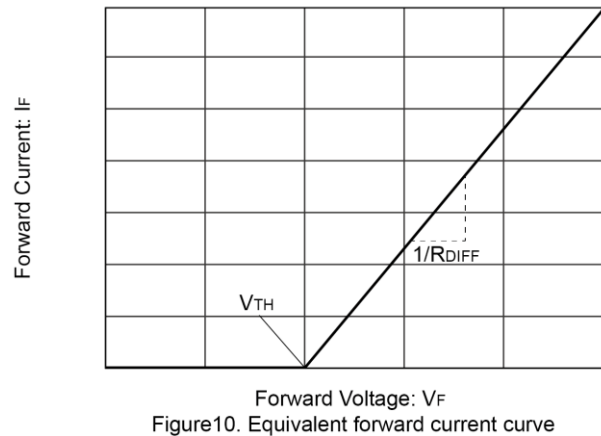
**E<sub>C</sub> – V<sub>R</sub> Characteristics**



**Typical Transient Thermal Resistance vs. Pulse Width**



**Simplified Forward Characteristic**



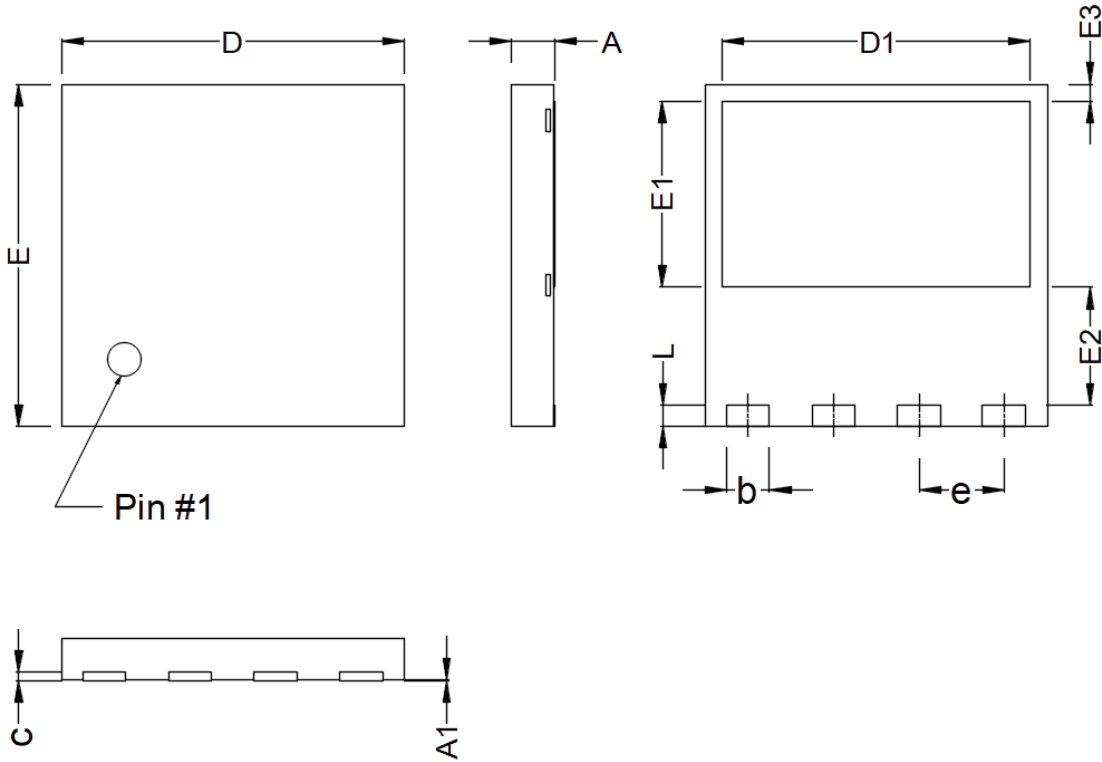
$$V_F = V_{TH} + R_{DIFF} \times I_F$$

**Threshold Voltage(V<sub>TH</sub>):**  
 $V_{TH}(T_j) = -0.0019 \times T_j + 0.78 [V]$

**Differential Resistance(R<sub>DIFF</sub>):**  
 $R_{DIFF}(T_j) = A \times T_j^2 + B \times T_j + C [\Omega]$   
 $A = 2.0 \times 10^{-6}$   
 $B = 1.0 \times 10^{-4}$   
 $C = 4.21 \times 10^{-2}$



**Package Outline**



Unit : mm

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.90	1.00	1.10
c	0.10	0.20	0.30
D	7.90	8.00	8.10
D1	7.10	7.20	7.30
E	7.90	8.00	8.10
E1	4.25	4.35	4.45
E2	2.65	2.75	2.85
E3	0.30	0.40	0.50
e	2.00 BSC		
L	0.40	0.50	0.60